

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT																
NATURE OF CONVEYANCE:	ASSIGNMENT																
CONVEYING PARTY DATA																	
<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 70%;">Name</th> <th style="width: 30%;">Execution Date</th> </tr> </thead> <tbody> <tr><td>Jae-Han CHA</td><td>05/13/2010</td></tr> <tr><td>Kyung-Ho LEE</td><td>05/13/2010</td></tr> <tr><td>Sun-Goo KIM</td><td>05/13/2010</td></tr> <tr><td>Hyung-Suk CHOI</td><td>05/13/2010</td></tr> <tr><td>Ju-Ho KIM</td><td>05/13/2010</td></tr> <tr><td>Jin-Young CHAE</td><td>05/13/2010</td></tr> <tr><td>In-Taek OH</td><td>05/13/2010</td></tr> </tbody> </table>		Name	Execution Date	Jae-Han CHA	05/13/2010	Kyung-Ho LEE	05/13/2010	Sun-Goo KIM	05/13/2010	Hyung-Suk CHOI	05/13/2010	Ju-Ho KIM	05/13/2010	Jin-Young CHAE	05/13/2010	In-Taek OH	05/13/2010
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<table border="1" style="width: 100%; border-collapse: collapse;"> <tr><td>Name:</td><td>MAGNACHIP SEMICONDUCTOR, LTD.</td></tr> <tr><td>Street Address:</td><td>1 Hyangjeong-dong, Heungduk-gu</td></tr> <tr><td>City:</td><td>Cheongju-si, Chungcheongbuk-do</td></tr> <tr><td>State/Country:</td><td>REPUBLIC OF KOREA</td></tr> <tr><td>Postal Code:</td><td>361-725</td></tr> </table>		Name:	MAGNACHIP SEMICONDUCTOR, LTD.	Street Address:	1 Hyangjeong-dong, Heungduk-gu	City:	Cheongju-si, Chungcheongbuk-do	State/Country:	REPUBLIC OF KOREA	Postal Code:	361-725						
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CORRESPONDENCE DATA																	
<p>Fax Number: (703)773-5200 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i></p> <p>Phone: 7037734149 Email: bert.lee@dlapiper.com Correspondent Name: Dale Lazar Address Line 1: P.O. Box 2758 Address Line 4: Reston, VIRGINIA 20195</p>																	
ATTORNEY DOCKET NUMBER:	312973-000257																

OP \$40.00 12835514

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PATENT
REEL: 024676 FRAME: 0906

NAME OF SUBMITTER:

Bert Lee

Total Attachments: 2

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ASSIGNMENT OF APPLICATION

WHEREAS, I/we,

Jae-Han CHA of Cheongju-Si, Republic of KOREA,
Kyung-Ho LEE of Cheongju-Si, Republic of KOREA,
Sun-Goo KIM of Cheongju-Si, Republic of KOREA,
Hyung-Suk CHOI of Cheongju-Si, Republic of KOREA,
Ju-Ho KIM of Cheongju-Si, Republic of KOREA,
Jin-Young CHAE of Cheongju-Si, Republic of KOREA,
In-Taek OH of Cheongju-Si, Republic of KOREA,

respectively; have invented certain new and useful improvements in: "SEMICONDUCTOR DEVICE" (hereinafter referred to as the "Invention"), for which an application for Letters Patent was filed on July 13, 2010 (Application No. 12/835,514),); and

WHEREAS, **MagnaChip Semiconductor, Ltd.**, (hereinafter referred to as "ASSIGNEE"), having a place of business at 1 Hyangjeong-dong, Heungduk-gu, Cheongju-si, Chungcheongbuk-do, 361-725, Republic of KOREA, is desirous of acquiring the full and exclusive right in and to said Invention and the entire right, title and interest in and to any and all Letters Patent which may be granted therefor in the United States and its territorial possessions and in any and all foreign countries;

NOW, THEREFORE, in consideration of the sum of FIVE DOLLARS (\$5.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration, I/we, by these presents do sell, assign and transfer unto said ASSIGNEE, the full and exclusive right in and to said Invention in the United States and its territorial possessions and in any and all foreign countries, and the entire right, title and interest in and to any and all Letters Patent which may be granted therefor in the United States and its territorial possessions and in any and all foreign countries and in and to any and all subsequent applications based thereon including any and all divisions, continuations, substitutions, renewals and reissues thereof together with the right of priority under the International Convention for the Protection of Industrial Property, Inter-American Convention relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres.

I/we hereby authorize and request the Patent Office Officials in the United States and its territorial possessions and in any and all foreign countries to issue any and all of said Letters Patent, when granted, to said ASSIGNEE as the assignee of my/our entire right, title and interest in and to the same, for the sole use and behoof of said ASSIGNEE and said ASSIGNEE's successors and assigns, to the full end of the term for which said Letters Patent may be granted, as fully and entirely as the same would have been held by me/us had this Assignment and sale not been made.

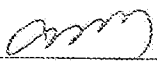
Further, I/we agree that I/we will communicate to said ASSIGNEE or said ASSIGNEE's representatives any facts known to me/us respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuation, substitute, renewal and reissue applications, execute all necessary assignment papers to cause any and all of said Letters Patent to be issued to said ASSIGNEE, make all rightful oaths, and, generally, do everything possible to aid said ASSIGNEE, and said ASSIGNEE's successors and assigns, to obtain and enforce proper protection for said Invention in the United States and its territorial possessions and in any and all foreign countries.

The undersigned hereby grant(s) the firm of DLA Piper US LLP, Attorneys at Law, 1775 Wiehle Avenue, Suite 400, Reston, Virginia 20190-5159, the power to insert on this Assignment any further identification, including the application number and filing date, which may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for recordation of this document.

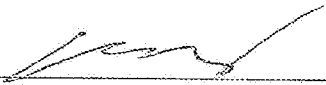
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Jae-Han CHA

Date: 2010.5.13


Kyung-Ho LEE

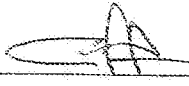
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Sun-Goo KIM

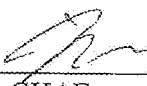
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Hyung-Suk CHOI

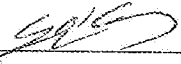
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Ju-Ho KIM

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Jin-Young CHAE

Date: 2010.5.13


In-Taek OH